In the Claims:

1-11. (Canceled).

12. (Previously Presented) A process for fabricating an integrated circuit package, comprising:

providing a substrate having opposing first and second surfaces and conductive traces extending therebetween, the substrate having a cavity therein;

providing a ground ring on an inside of the cavity, the ground ring comprising,

a first ground ring portion, accessible from the first surface of the substrate,

a second ground ring portion, accessible from the second surface of the substrate, and

a ground ring trace portion, to electrically connect the first ground ring portion to the second ground ring portion;

fixing a heat slug in the form of a substantially flat plate to said first surface of said substrate, such that said heat slug spans said cavity;

mounting a semiconductor die to said heat slug, said semiconductor die being disposed in said cavity;

wire bonding said semiconductor die to ones of said conductive traces at said second surface of said substrate;

encapsulating said wire bonds and said semiconductor die in an encapsulating material; and

forming a ball grid array on said first surface of said substrate such that bumps of said ball grid array are in electrical connection with ones of said conductive traces;

wherein the heat slug is fixed to the first surface of the substrate on which said ball grid array is formed; and

wherein said substrate is substantially the same thickness as said semiconductor die.

13. (Canceled)

14. (Previously Presented) The process for fabricating an integrated circuit package according to claim 12, wherein fixing said heat slug to said substrate comprises fixing said heat slug to said substrate by solder reflow technique.

15. (Currently Amended) The [[A]] process for fabricating an integrated circuit package [[,]] according to claim 12, further comprising

~~: providing a substrate having opposing first and second surfaces and conductive traces extending therebetween, the substrate having a cavity therein;~~

~~fixing a heat slug in the form of a substantially flat plate to said first surface of said substrate, such that said heat slug spans said cavity;~~

~~mounting a semiconductor die to said heat slug, said semiconductor die being disposed in said cavity;~~
mounting a die adapter to said semiconductor die, prior to encapsulating.

~~; wire bonding said semiconductor die to ones of said conductive traces at said second surface of said substrate;~~

~~encapsulating said wire bonds, said semiconductor die, and at least a portion of said die adapter in an encapsulating material; and~~

~~forming a ball grid array on said first surface of said substrate such that bumps of said ball grid array are in electrical connection with ones of said conductive traces;~~

~~wherein said substrate is substantially the same thickness as said semiconductor die.~~

16. (Original) The process for fabricating an integrated circuit package according to claim 15, wherein, encapsulating comprises encapsulating said wire bonds and said semiconductor die and surrounding said die adapter such that a surface of said die adapter is exposed.

17. (Original) The process for fabricating an integrated circuit package according to claim 12, further comprising mounting a heat spreader to said substrate, prior to encapsulating.

18. (Original) The process for fabricating an integrated circuit package according to claim 15, further comprising mounting a heat spreader to said substrate, prior to encapsulating.

19. (Original) The process for fabricating an integrated circuit package according to claim 16, further comprising mounting a heat spreader, prior to encapsulating, such that at least one side wall of said heat spreader is mounted to said substrate and a top portion of said heat spreader contacts said die adapter.

20. (Canceled)

21. (Previously Presented) A process for fabricating an integrated circuit package, comprising:

providing a substrate having opposing first and second surfaces and conductive traces extending therebetween, the substrate having a cavity therein;

providing a ground ring on an inside of the cavity, the ground ring comprising,

a first ground ring portion, accessible from the first surface of the substrate,

a second ground ring portion, accessible from the second surface of the substrate, and a ground ring trace portion, to electrically connect the first ground ring portion to the second ground ring portion;

fixing a heat slug in the form of a substantially flat plate to said first ground ring portion, such that said heat slug spans said cavity;

mounting a semiconductor die to said heat slug, said semiconductor die being disposed in said cavity;

wire bonding said semiconductor die to ones of said conductive traces at said second surface of said substrate;

encapsulating said wire bonds and said semiconductor die in an encapsulating material; and

forming a ball grid array on said first surface of said substrate such that bumps of said ball grid array are in electrical connection with ones of said conductive traces;

wherein said substrate and said ground ring are substantially the same thickness as said semiconductor die.